



Material Content Data Sheet



Sales Product Name				IPD60R750E6		Issued		17. October 2014	
MA#				MA001182908					
Package				PG-TO252-3-313		Weight*		318.51 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.737	0.86	0.86	8592	8592	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		462		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	copper	7440-50-8	147.096	46.18	46.24	461827	462428	
wire	non noble metal	aluminium	7429-90-5	0.511	0.16	0.16	1604	1604	
encapsulation	organic material	carbon black	1333-86-4	1.410	0.44		4426		
	plastics	epoxy resin	-	24.669	7.75		77452		
	inorganic material	silicondioxide	60676-86-0	114.888	36.07	44.26	360705	442583	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11742	11742	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4460	4471	
solder	noble metal	silver	7440-22-4	0.066	0.02		207		
	non noble metal	tin	7440-31-5	0.053	0.02		166		
	non noble metal	lead	7439-92-1	2.522	0.79	0.83	7919	8292	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60210	60288	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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